



# ACE5801

## P-Channel Power MOSFET

### Description

The ACE5801 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with low gate voltage.

. This device is suitable for use as a load switching application and a wide variety of other applications.

### Features

- Advanced trench MOSFET process technology
- Ultra low on-resistance with low gate charge

### Applications

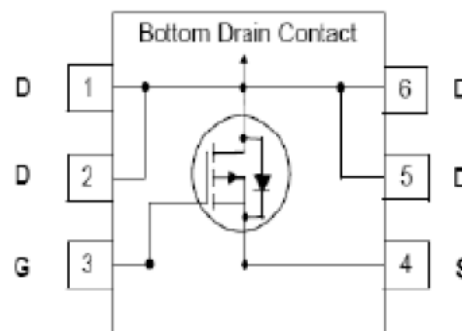
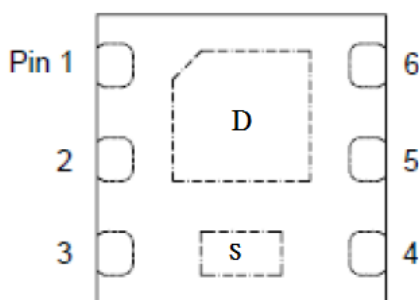
- PWM application
- Load switch
- Battery charge in cellular handset

### Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Drain-Source Voltage	$V_{DSS}$	-12	V
Gate-Source Voltage	$V_{GSS}$	$\pm 8$	V
Drain Current-Continuous	$I_D$	-16	A
Drain Current-Pulsed (note 1)	$I_{DM}$	-65	
Power Dissipation (note 2, $T_A=25^\circ\text{C}$ )	$P_D$	2.5	W
Maximum Power Dissipation (note 3, $T_C=25^\circ\text{C}$ )		18	
Thermal Resistance from Junction to Ambient (note 4)	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to case (note 4)	$R_{\theta JC}$	6.9	
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~150	

### Packaging Type

DFNWB2\*2-6L



1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

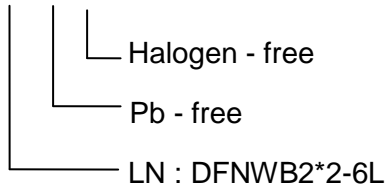


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### Ordering information

ACE5801 XX + H



### Electrical Characteristics (T<sub>A</sub>=25 °C unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Off characteristics						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-12			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V			-1	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V			±100	nA
On characteristics (note 5)						
Drain-Source On-state Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-6.7A			21	mΩ
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-6.2A			27	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250uA	-0.4	-0.7	-1	V
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-10V, I <sub>D</sub> =-6.7A		40		S
Dynamic characteristics (note 6)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =-10V, V <sub>GS</sub> =0V f=1 MHz		2700		pF
Output Capacitance	C <sub>oss</sub>			680		
Reverse Transfer Capacitance	C <sub>rss</sub>			590		
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =-6V, V <sub>GS</sub> =-8V, I <sub>D</sub> =-10A		60	100	nC
		V <sub>DS</sub> =-6V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A		35	48	
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> =-6V, V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-10A		5		
Gate-Drain Charge	Q <sub>gd</sub>			10		
Drain-source diode characteristics						
Diode Forward Current (note 5)	I <sub>S</sub>				-16	A
Diode Forward Voltage (note 4)	V <sub>SD</sub>	I <sub>S</sub> =-1.6A, V <sub>GS</sub> =0V	-0.5		-1.2	V

Note:

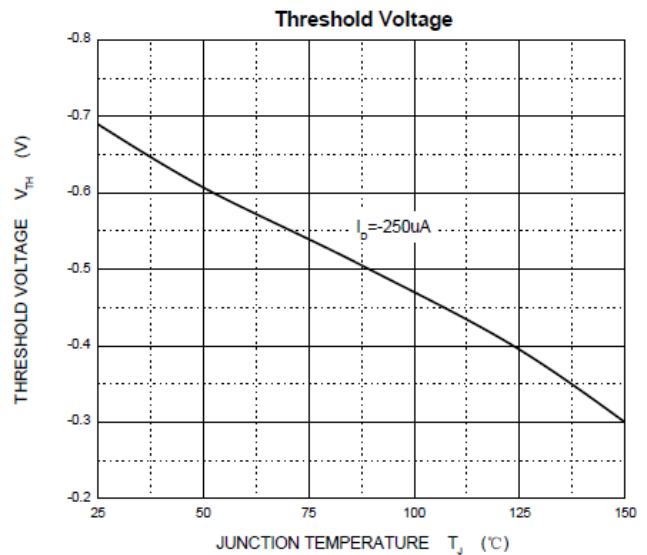
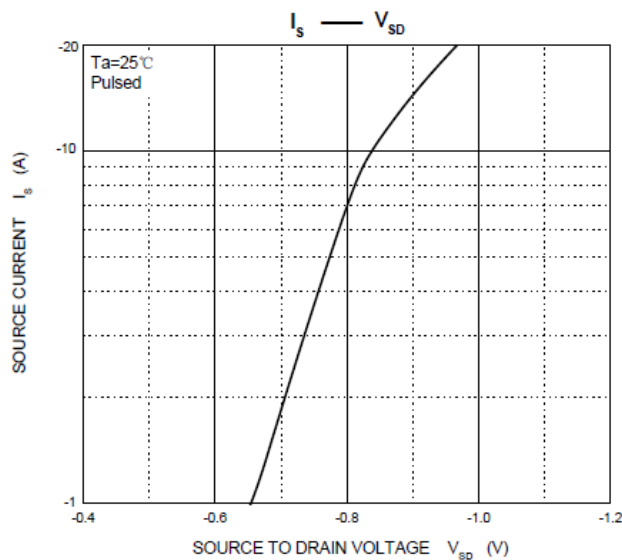
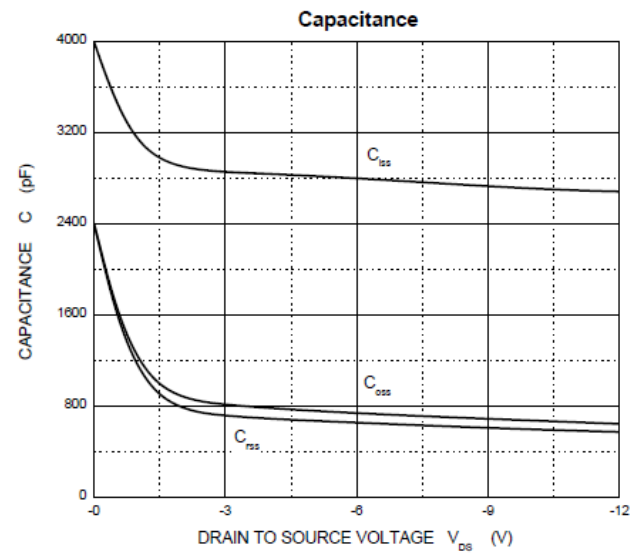
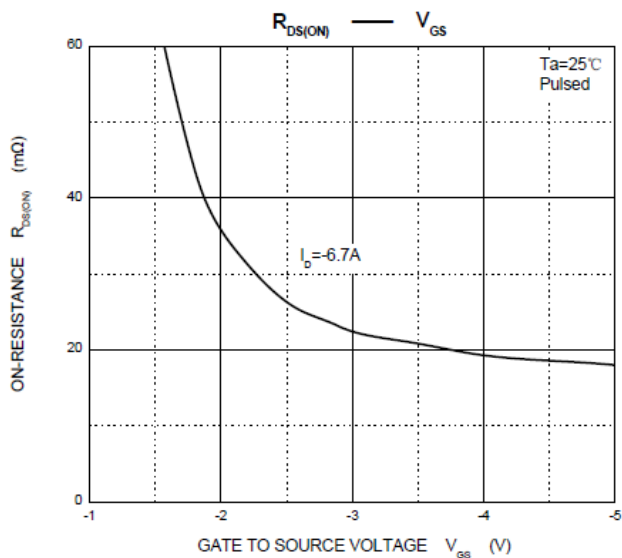
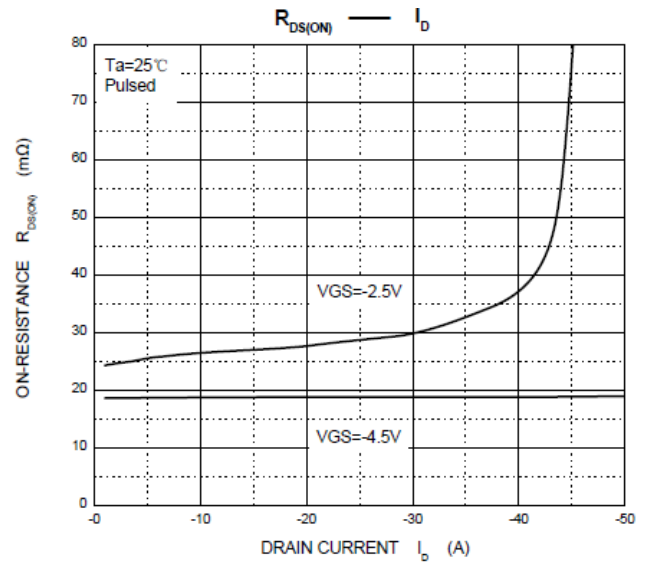
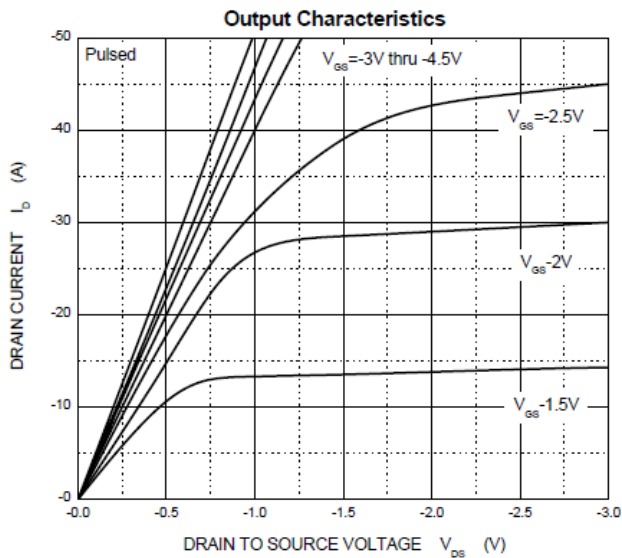
1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. This test is performed with no heat sink at T<sub>a</sub>=25°C.
3. This test is performed with infinite heat sink at T<sub>c</sub>=25°C.
4. Surface mounted on FR4 board, t<sub>s</sub>≤10S.
5. Pulse Test: Pulse With ≤300us, Duty Cycle≤2%.
6. Guaranteed by design, not subject to production testing.



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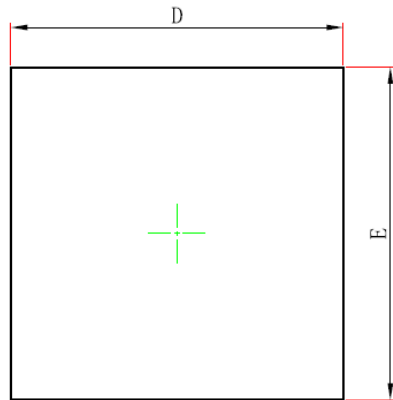
### Typical Performance Characteristics



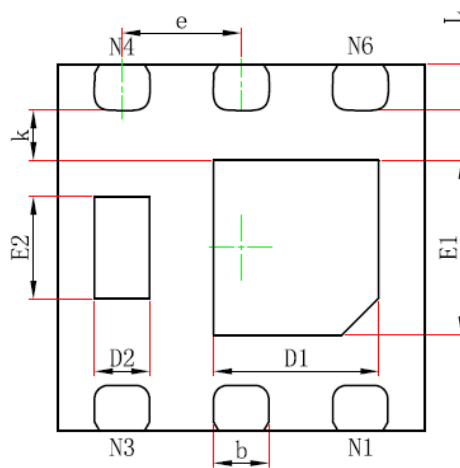


**Packing Information**

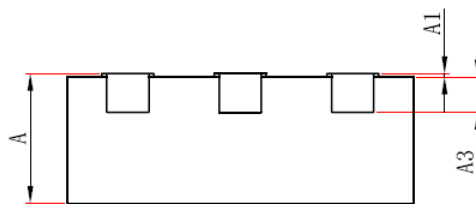
**DFNWB2\*2-6L**



TOP VIEW



BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.924	2.076	0.076	0.082
E	1.924	2.076	0.076	0.082
D1	0.800	1.000	0.031	0.039
E1	0.850	1.050	0.033	0.041
D2	0.200	0.400	0.008	0.016
E2	0.460	0.660	0.018	0.026
k	0.200MIN.		0.008MIN.	
b	0.250	0.350	0.010	0.014
e	0.650TYP.		0.026TYP.	
L	0.174	0.326	0.007	0.013



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### Notes

ACE does not assume any responsibility for use as critical components in life support devices or systems without the express written approval of the president and general counsel of ACE Electronics Co., LTD. As sued herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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